

AMENDMENTS TO THE SPECIFICATION

Please replace [0043] with the amended paragraph below, correcting a typographical error.

[0043] As the material of the resin molding W in the present invention there may be used any of all the materials used in the production of resin-plated parts, including ABS resin, PC/ABS resin (polycarbonate/AGS ~~ABS~~ resin), PC/PET resin (polycarbonate/polyethylene terephthalate resin), PC/PBT (polycarbonate/polybutylene terephthalate resin), PC resin, PA resin (polyamide resin), POM resin (polyoxymethylene resin), PPE resin (polyphenylene ether resin), LCP resin (liquid crystalline polymer resin), PPS resin (polyphenylene sulfide resin), PS resin (polystyrene resin), and SPS resin (syndiotactic polystyrene resin). No limitation is made thereto. An appropriate heat treatment temperature differs depending on the resin material used. As noted in the foregoing paragraph of background art, the heating method of the present invention is effectively applicable to a resin molding W comprising two or more different resins and containing a rubbery or oil- or fat-like substance which is apt to appear in the resin molding W.